Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.046”**

**.046”**

**Anode**

**.025 X .025”**

**Top Material: Al**

**Backside Material: TiNiAg**

**Bond Pad Size: .025” X .025”**

**Backside Potential: Cathode**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .046” X .046” DATE: 1/26/23**

**MFG: ON SEMI / MOTOROLA THICKNESS .015” P/N: MURC150**

**DG 10.1.2**

#### Rev B, 7/19/02